

2W Stereo Audio Power Amplifier with Shutdown Mode

General Description

The EMA1201 is a stereo bridged audio power amplifier capable of delivering 1.2W of continuous average power into a 8Ω load or 1.7W into 4Ω with less than 1% THD when powered by a 5V power supply. It does not require output coupling capacitors or bootstrap capacitors, and is ideal for mobile phone and other low voltage applications where minimal power consumption is a primary requirement.

The EMA1201 features a low-power consumption shutdown mode, and an internal thermal shutdown protection mechanism. Advanced pop & click circuitry is built in to eliminate noises that would otherwise occur during turn-on and turn-off transitions. The EMA1201 is unity-gain stable and can be configured by external gain-setting resistors.

EMP products are Pb-free and RoHS compliant.

- BTL mode Po at THD+N=1%, f=1kHz, V_{DD} =5V 1.7 W (typ) into 4Ω 1.2 W (typ) into 8Ω
- BTL mode Po at THD+N=10%, f=1kHz, V_{DD} =5V 2 W (typ) into 4Ω 1.5 W (typ) into 8Ω
- · Shutdown current 0.1µA (typ)

Features

- No output coupling capacitors, bootstrap capacitors, or snubber circuits required
- · Unity-gain stable
- TQFN
- · External gain configuration capability

Applications

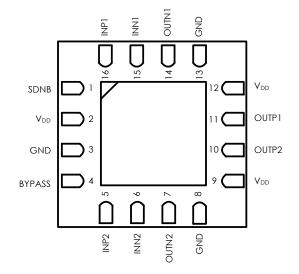
- · Portable Computers
- · Desktop computers

Key Specifications



Connection Diagram

TQFN Package



Order information

EMA1201-50HB16GRR/NRR

50 5.0V Operation HB16 TQFN-16 Package

(EB16)

GRR RoHS (Pb Free)

Rating: -40 to 85°C Package in Tape & Reel

NRR RoHS & Halogen free (By Request)

Rating: -40 to 85°C

Package in Tape & Reel

Order, Mark & Packing Information

Package	Product ID	Marking	Packing
TQFN-16	EMA1201-50HB16GRR	SEMP CONTROL OF STAND ST	5K units Tape & Reel



Typical Application

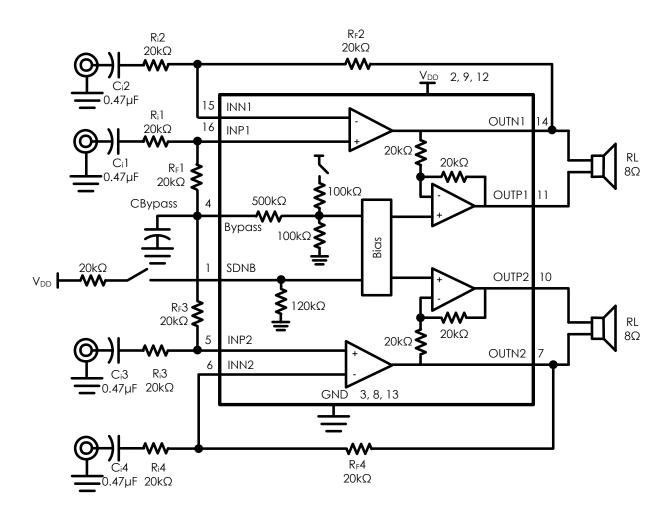


FIGURE 2. Typical Audio Amplifier Application Circuit with differential input



Absolute Maximum Ratings

Supply Voltage Storage Temperature Input Voltage Power Dissipation ESD Susceptibility

Junction Temperature

6.0V -65°C to +150°C -0.3V to VDD +0.3V Internally Limited HBM 2kV MM 200V

150°C

Thermal Resistance θ_{JA} (TQFN)

190°C/W

Operating Ratings

Temperature Range -40°C Supply Voltage 2.5V

-40°C \leq TA \leq 85°C 2.5V \leq VDD \leq 5.5V

Electrical Characteristics

The following specifications apply for $V_{DD} = 5V$ and $R_L = 8\Omega$ unless otherwise specified. Limits apply for $T_A = 25^{\circ}C$.

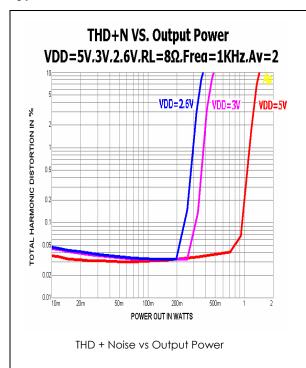
	- 1117		Conditions			Units
Symbol	Parameter	Conditions	Min	Typical	Limit	(Limits)
I _{DD}	Quiescent Power Supply Current	V _{IN} = 0V, Io = 0A		3.5	8.0	mA
I _{SD}	Shutdown Current	$V_{SDNB} = GND$		0.1	1.0	μΑ
Vos	Output Offset Voltage	$V_{IN} = 0V$		5.0	50	mV
Ро	Output Power	$THD + N = 1 \%, f = 1 kHz$ $R_L = 4 \Omega$ $R_L = 8 \Omega$ $THD + N = 10 \%, f = 1 kHz$ $R_L = 4 \Omega$ $R_L = 8 \Omega$		1.7 1.2 2.0 1.5		W
THD+N	Total Harmonic Distortion + Noise	$f = 1 \text{ kHz}, \text{ AV=2, P}_0 = 0.25 \text{W}$ $R_L = 8 \Omega$	-			%
PSRR	Power Supply Rejection Ratio	V_{RIPPLE} =200mV, sine p-p at 217Hz, input 10 Ω to GND		60	55	dB

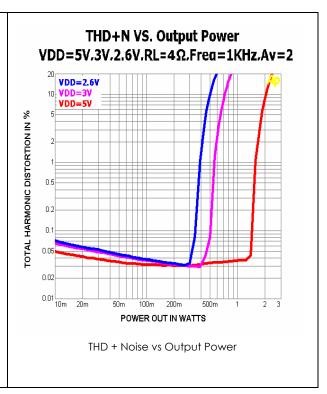
The following specifications apply for V_{DD} = 2.6V and R_L = 8 Ω unless otherwise specified. Limits apply for T_A = 25 $^{\circ}$ C.

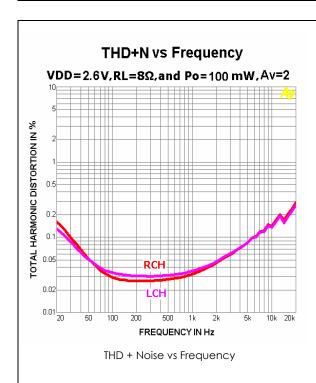
			Conditions			Units
Symbol	Parameter	Conditions	Min	Typical	Limit	(Limits)
I _{DD}	Quiescent Power Supply Current	V _{IN} = 0V, Io = 0A		2.5	5.0	mA
I _{SD}	Shutdown Current	$V_{SDNB} = GND$		0.1	1.0	μΑ
V_{OS}	Output Offset Voltage	$V_{IN} = 0V$		5.0	50	mV
Ро	Output Power	$THD + N = 1 \%, f = 1 \text{ kHz}$ $R_L = 4 \Omega$ $R_L = 8 \Omega$ $THD + N = 10 \%, f = 1 \text{ kHz}$ $R_L = 4 \Omega$ $R_L = 8 \Omega$		0.4 0.3 0.5 0.38		W
THD+N	Total Harmonic Distortion + Noise	$f = 1 \text{kHz}, \text{ AV=2, P}_{\odot} = 0.1 \text{W}$ $R_L = 8 \Omega$	0.03			%
PSRR	Power Supply Rejection Ratio	V_{RIPPLE} =200mV, sine p-p at 217Hz, input 10 Ω to GND		60	55	dB

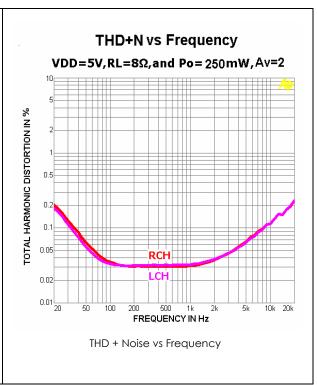


Typical Performance Characteristics

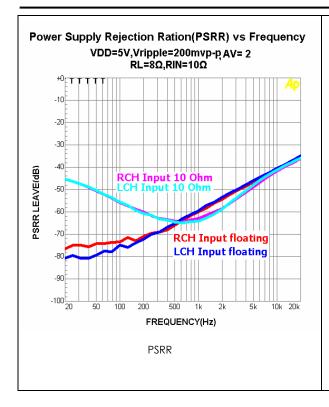


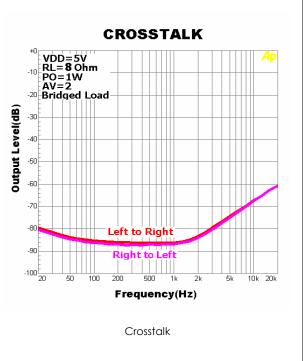


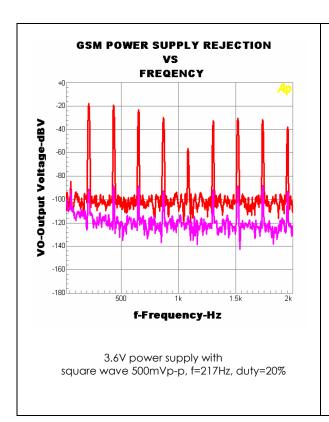






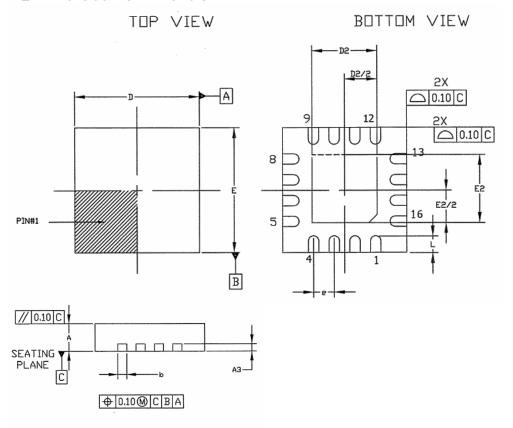








TQFN-16 Outline Dimension



SIDE VIEW

S	COMMON						
M B C	DIMENSIONS MILLIMETER			DIMENSIONS INCH			
Ľ	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.	
Α	0.70	0.75	0.80 🗸	0.027	0.029	0.031	
А3	0.195	0.203	0.211	0.0077	0.008	0.0083	
b	0.18	0.23	0.30	0.007	0.009	0.012	
D	2.95	3.0 <	3.05	0.116	0.118	0.120	
Ε	2.95	3.0 <	3.05	0.116	0.118	0.120	
е	0.50 BSC			C	.020 BS		
L	0.35	0.40	0.45	0.014	0.016	0.018	

Ş		D2/E2			D2/E2		
M B		DIMENSIONS MILLIMETER			DIMENSIONS INCH		
D L		MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
PTION	1	1.50/1.50	1.625/1.625	1.75/1.75	0.059/0.059	0.064/0.064	0.069/0.069



Revision History

Revision	Date	Description
4.0	2009.06.05	EMP transferred from version 3.0



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Publication Date: Mar. 2009 Revision: 4.0 9/9